

## C1206C271JATACTU

Aliases (C1206C271JATAC7800) SMD Comm X8G HT150C, Ceramic, 270 pF, 5%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

270 pF

100 GOhms

Dimensions		Specifications
Chip Size	1206	Capacitance
L	3.2mm +/-0.2mm	Measurement Condit
W	1.6mm +/-0.2mm	Tolerance
т	0.78mm +/-0.10mm	Voltage DC
S	1.5mm MIN	Dielectric Withstandi
В	0.5mm +/-0.25mm	Temperature Range
		Temp. Coefficient
Packaging Specifications		Capacitance Change

3.2mm +/-0.2mm	Measurement Condition	1 MHz 1.0Vrms
1.6mm +/-0.2mm	Tolerance	5%
0.78mm +/-0.10mm	Voltage DC	250 VDC
1.5mm MIN	Dielectric Withstanding Voltage	625 VDC
0.5mm +/-0.25mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
T&R, 180mm, Plastic Tape 4000	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

Insulation Resistance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Packaging

Packaging Quantity